

## Product Summary

<b>V<sub>BR_MIN</sub></b>	<b>I<sub>PP_MAX</sub></b>	<b>C<sub>IN_TYP</sub></b>
5V	3A	0.17pF

## Description

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as USB3.1 and Thunderbolt 3.

## Applications

- USB3.1
- Thunderbolt 3
- Computers and Peripheral

## Features

- Provides ESD Protection per IEC 61000-4-2 Standard:  
Air ±8kV, Contact ±8kV
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

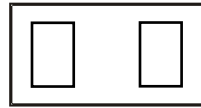
## Mechanical Data

- Case: X2-DSN0603-2
- Case Material: Chip Scale Package
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 <sup>(e4)</sup>
- Weight: 0.0002 grams (Approximate)

X2-DSN0603-2



Top View



Bottom View



Device Schematic

## Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DESD3V3Z1BCSF-7	Standard	MZ	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free/](http://www.diodes.com/quality/lead_free/) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



MZ = Product Type Marking Code  
Bar Denotes Pin 1

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Condition
Peak Pulse Power Dissipation	P <sub>PP</sub>	25	W	8/20μs, per Figure 3
Peak Pulse Current	I <sub>PP</sub>	3	A	8/20μs, per Figure 3
ESD Protection – Air Discharge	V <sub>ESD_AIR</sub>	±8	kV	IEC61000-4-2 Standard
ESD Protection – Contact Discharge	V <sub>ESD_CONTACT</sub>	±8	kV	IEC61000-4-2 Standard

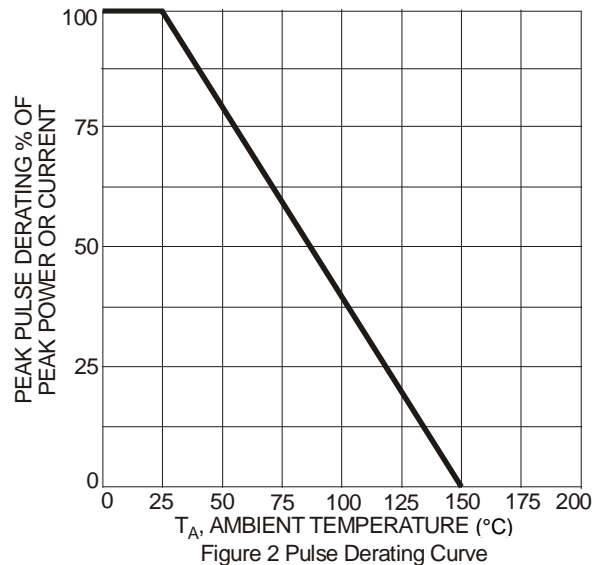
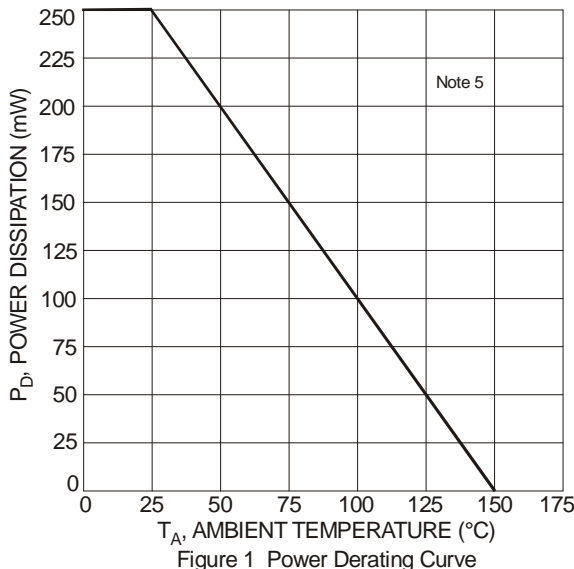
**Thermal Characteristics**

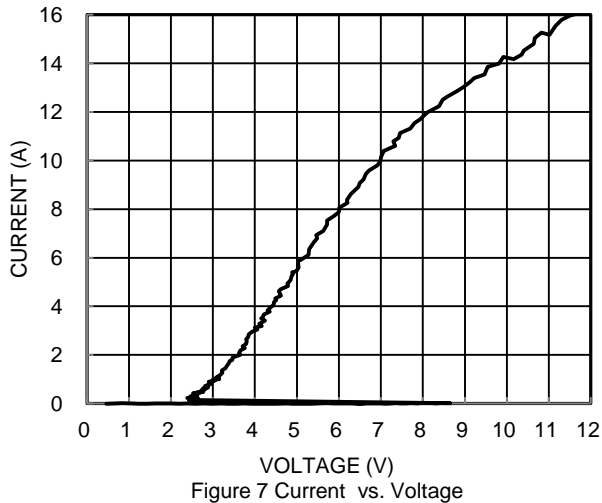
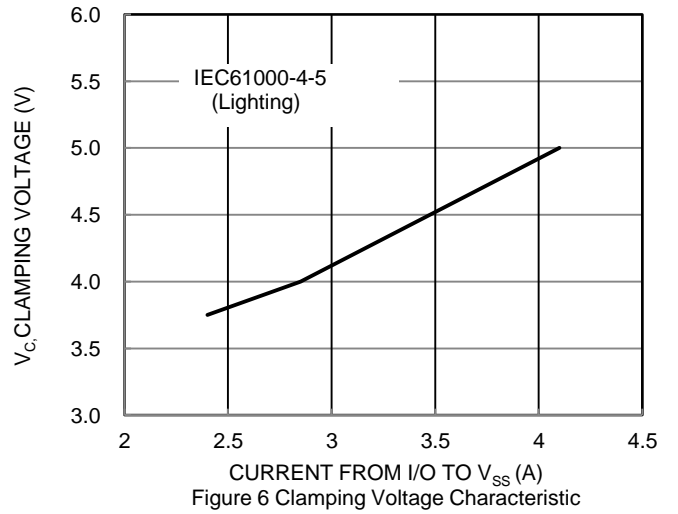
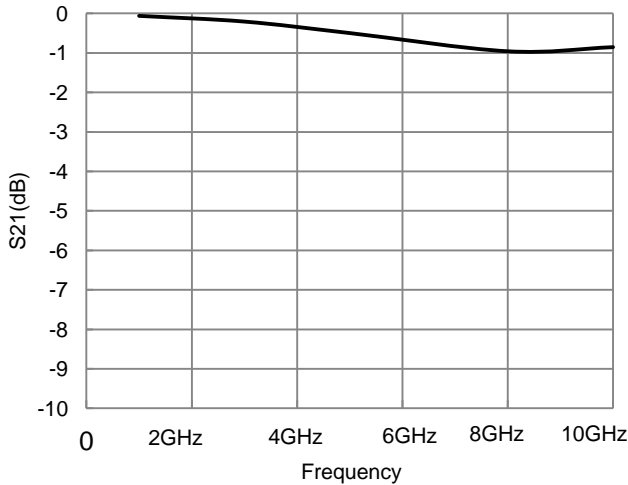
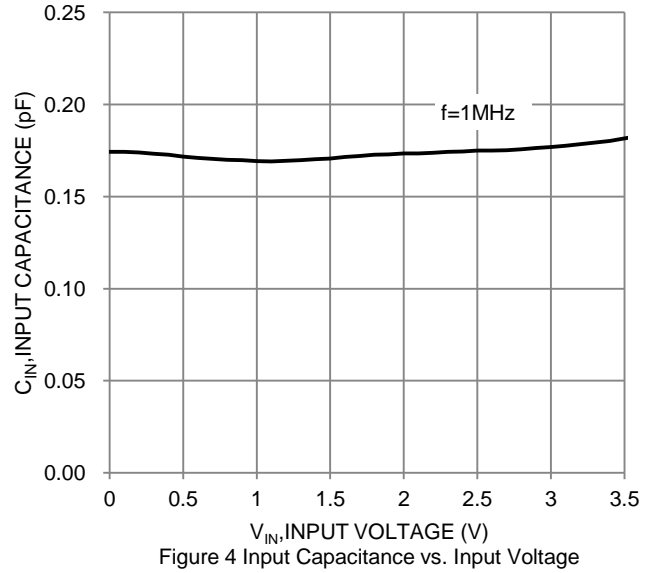
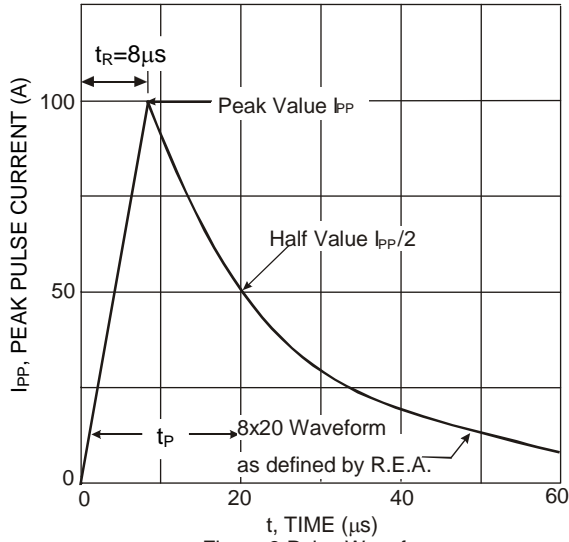
Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ.	Max	Unit	Test Conditions
Reverse Standoff Voltage	V <sub>RWM</sub>	—	—	3.3	V	—
Channel Leakage Current (Note 6)	I <sub>RM</sub>	—	—	1	μA	V <sub>RWM</sub> = 3.3V
Clamping Voltage	V <sub>CL</sub>	—	4.5	—	V	I <sub>PP</sub> = 3A, t <sub>p</sub> = 8/20μs
		—	6.0	—		I <sub>PP</sub> = 8A, TLP, t <sub>p</sub> = 100ns
		—	11.5	—		I <sub>PP</sub> = 16A, TLP, t <sub>p</sub> = 100ns
Breakdown Voltage	V <sub>BR</sub>	5	—	9	V	I <sub>R</sub> = 1mA
Differential Resistance	R <sub>DYN</sub>	—	0.4	—	Ω	TLP, 10A, t <sub>p</sub> = 100ns
Channel Input Capacitance	C <sub>IN</sub>	—	0.17	0.25	pF	V <sub>R</sub> = 0V, f = 1MHz

- Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
6. Short duration pulse test used to minimize self-heating effect.

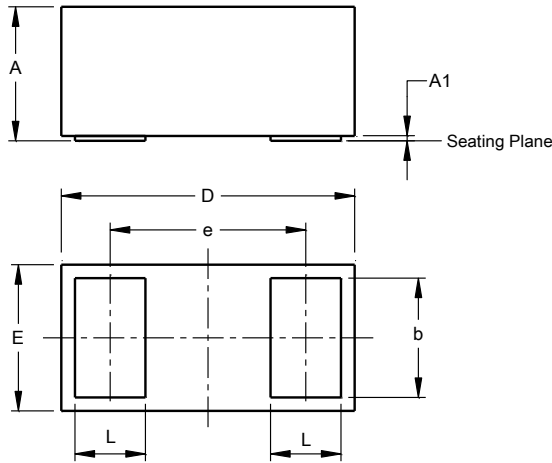




**Package Outline Dimensions** (Note 7)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DSN0603-2**



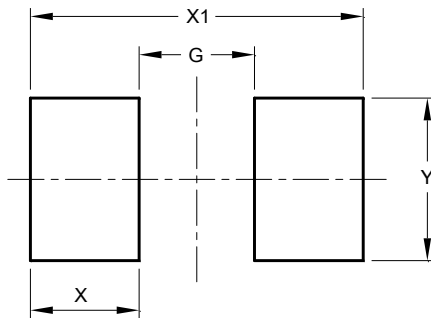
X2-DSN0603-2			
Dim	Min	Max	Typ
A	0.280	0.320	0.300
A1	0.00	0.020	0.010
b	0.220	0.260	0.240
D	0.575	0.625	0.600
E	0.275	0.325	0.300
e	-	-	0.400
L	0.120	0.160	0.140
All Dimensions in mm			

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X2-DSN0603-2**



Dimensions	Value (in mm)
G	0.206
X	0.194
Y	0.291
X1	0.594